



SLOVENSKI STANDARD

SIST EN 62132-8:2012

01-december-2012

Integrirana vezja - Meritve elektromagnetne odpornosti - 8. del: Meritev odpornosti proti sevanju - Metoda z IC na tračnem valovodu

Integrated circuits - Measurement of electromagnetic immunity - Part 8: Measurement of radiated immunity - IC stripline method

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Circuits intégrés - Mesure de l'immunité électromagnétique - Partie 8: Mesure de l'immunité rayonnée - Méthode de la ligne à ruban pour circuit intégré

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31.200

Integrirana vezja,
mikroelektronika

Integrated circuits.
Microelectronics

SIST EN 62132-8:2012

en

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EUROPEAN STANDARD
NORME EUROPÉENNE
EUROPÄISCHE NORM

EN 62132-8

September 2012

ICS 31.200

English version

**Integrated circuits -
Measurement of electromagnetic immunity -
Part 8: Measurement of radiated immunity -
IC stripline method
(IEC 62132-8:2012)**

Circuits intégrés -
Mesure de l'immunité électromagnétique -
Partie 8: Mesure de l'immunité rayonnée -
Méthode de la ligne TEM à plaques pour
circuit intégré
(CEI 62132-8:2012)

Integrierte Schaltungen -
Messung der elektromagnetischen
Störfestigkeit -
Teil 8: Messung der Störfestigkeit bei
Einstrahlungen -
IC-Streifenleiterverfahren
(IEC 62132-8:2012)

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CENELEC

European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

Management Centre: Avenue Marnix 17, B - 1000 Brussels

Foreword

The text of document 47A/882/FDIS, future edition 1 of IEC 62132-8, prepared by SC 47A, "Integrated circuits", of IEC TC 47, "Semiconductor devices" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 62132-8:2012.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2013-05-10
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2015-08-10

This standard is to be used in conjunction with EN 62132-1.

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Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60050	Series	International Electrotechnical Vocabulary	-	-
IEC 61000-4-20	2010	Electromagnetic compatibility (EMC) - Part 4-20: Testing and measurement techniques - Emission and immunity testing in transverse electromagnetic (TEM) waveguides	EN 61000-4-20	2010
IEC 62132-1	2006	Integrated circuits - Measurement of electromagnetic immunity, 150 kHz to 1 GHz - Part 1: General conditions and definitions	EN 62132-1 + corr. November	2006 2006

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IEC 62132-8

Edition 1.0 2012-07

INTERNATIONAL STANDARD

NORME INTERNATIONALE



**Integrated circuits – Measurement of electromagnetic immunity –
Part 8: Measurement of radiated immunity – IC stripline method**

**Circuits intégrés – Mesure de l'immunité électromagnétique –
Partie 8: Mesure de l'immunité rayonnée – Méthode de la ligne TEM à plaques
pour circuit intégré**

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

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**INTEGRATED CIRCUITS –
MEASUREMENT OF ELECTROMAGNETIC IMMUNITY –**

**Part 8: Measurement of radiated immunity –
IC stripline method**

FOREWORD

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International Standard IEC 62132-8 has been prepared by subcommittee 47A: Integrated circuits, of IEC technical committee 47: Semiconductor devices.

The text of this standard is based on the following documents:

FDIS	Report on voting
47A/882/FDIS	47A/886/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

This part of IEC 62132 is to be read in conjunction with IEC 62132-1.

A list of all the parts in the IEC 62132 series, published under the general title *Integrated circuits – Measurement of electromagnetic immunity*, can be found on the IEC website.

Future standards in this series will carry the new general title as cited above. Titles of existing standards in this series will be updated at the time of the next edition.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC web site under "http://webstore.iec.ch" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
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